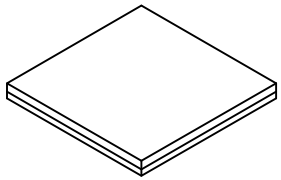
HMCCA,01/24/00,10:30:15,PBGAL2D101,M-01 RKRUT,09/05/00,16:28:23,HP517Q

REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
01	C9998	INITIAL RELEASE	RKRUT	RKRUT	09/05/00



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 225.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 15 X 15.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL X.X ±0.1 X.XX ±0.05 X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994

MATERIAL: N/A
FINISH: N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED SDEFO	06/12/00
CHECKED DARNO	06/12/00
PRODUCT MANAGER TPANC	06/12/00
RELEASED RHOLM	09/05/00

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE - MAF, 15 X 15 MATRIX, 13.00mm X 13.00mm X 1.40mm, 0.70mm MOLD CAP, 0.46mm BALL, 0.80mm PITCH, LAMINATE SUBSTRATE, AAWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	79822	01

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 3

FORM NO: MBFLAM1C1.DWG